3.3V CMOS Static RAM 1 Meg (64K x 16-Bit)

IDT71V016SA

Features

- 64K x 16 advanced high-speed CMOS Static RAM
- Equal access and cycle times
 - Commercial: 10/12/15/20ns
 - Industrial: 12/15/20ns
- One Chip Select plus one Output Enable pin
- Bidirectional data inputs and outputs directly LVTTL-compatible
- Low power consumption via chip deselect
- Upper and Lower Byte Enable Pins
- Single 3.3V power supply
- Available in 44-pin Plastic SOJ, 44-pin TSOP, and 48-Ball Plastic FBGA packages

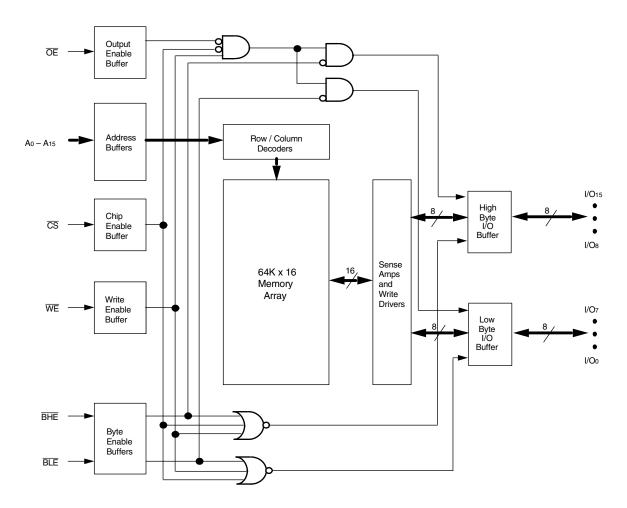
Description

The IDT71V016 is a 1,048,576-bit high-speed Static RAM organized as $64K \times 16$. It is fabricated using IDT's high-perfomance, high-reliability CMOS technology. This state-of-the-art technology, combined with innovative circuit design techniques, provides a cost-effective solution for high-speed memory needs.

The IDT71V016 has an output enable pin which operates as fast as 5ns, with address access times as fast as 10ns. All bidirectional inputs and outputs of the IDT71V016 are LVTTL-compatible and operation is from a single 3.3V supply. Fully static asynchronous circuitry is used, requiring no clocks or refresh for operation.

The IDT71V016 is packaged in a JEDEC standard 44-pin Plastic SOJ, a 44-pin TSOP Type II, and a 48-ball plastic 7 x 7 mm FBGA.

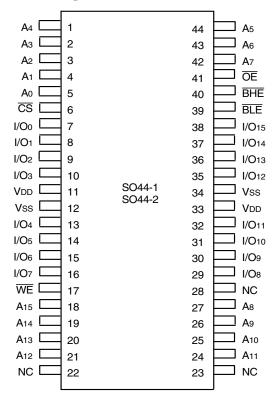
Functional Block Diagram



3834 drw 01

OCTOBER 2011

Pin Configurations



SOJ/TSOP Top View 3834 drw 02

	1	2	3	4	5	6
Α	BLE	Œ	A 0	A 1	A2	NC
В	1/08	BHE	Аз	A4	S	I/Oo
С	I/O9	I/O ₁₀	A 5	A 6	I/O ₁	I/O2
D	Vss	I/O ₁₁	NC	A 7	I/O3	VDD
Е	Vdd	I/O ₁₂	NC	NC	1/04	Vss
F	I/O ₁₄	I/O13	A 14	A 15	I/O ₅	I/O6
G	I/O ₁₅	NC	A 12	A 13	WE	I/O ₇
Н	NC	A 8	A 9	A 10	A 11	NC

FBGA (BF48-1) Top View

Pin Description

A0 - A15	Address Inputs	Input
<u>cs</u>	Chip Select	Input
WE	Write Enable	Input
ŌĒ	Output Enable	Input
BHE	High Byte Enable	Input
BLE	Low Byte Enable	Input
I/O0 - I/O15	Data Input/Output	I/O
VDD	3.3V Power	Power
Vss	Ground	Gnd

3834 tbl 01

3834 tbl 02a

Truth Table⁽¹⁾

Hatii	Iabic	•					
<u>cs</u>	ŌĒ	WE	BLE	BHE	I/O ₀ -I/O ₇	I/O8-I/O15	Function
Н	Х	Х	Х	Х	High-Z	High-Z	Deselected – Standby
L	L	Н	L	Н	DATAout	High-Z	Low Byte Read
L	L	Н	Н	L	High-Z	DATAout	High Byte Read
L	L	Н	L	L	DATAout	DATAout	Word Read
L	Х	L	L	L	DATAIN	DATAIN	Word Write
L	Х	L	L	Н	DATAIN	High-Z	Low Byte Write
L	Χ	L	Н	L	High-Z	DATAIN	High Byte Write
L	Η	Н	Х	Х	High-Z	High-Z	Outputs Disabled
L	X	Х	Н	Н	High-Z	High-Z	Outputs Disabled

NOTE:

1. $H = V_{IH}, L = V_{IL}, X = Don't care.$

3834 tbl 02

Absolute Maximum Ratings(1)

Symbol	Rating	Value	Unit
VDD	Supply Voltage Relative to Vss	–0.5 to +4.6	٧
VIN, VOUT	Terminal Voltage Relative to Vss	-0.5 to VDD+0.5	V
TBIAS	Temperature Under Bias	-55 to +125	°C
Тѕтс	Storage Temperature	-55 to +125	°C
Рт	Power Dissipation	1.25	W
Гоит	DC Output Current	50	mA

NOTE: 3834 tbl 03

Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
permanent damage to the device. This is a stress rating only and functional operation
of the device at these or any other conditions above those indicated in the operational
sections of this specification is not implied. Exposure to absolute maximum rating
conditions for extended periods may affect reliability.

Capacitance

(TA = +25°C, f = 1.0MHz, SOJ package)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
Cin	Input Capacitance	VIN = 3dV	6	pF
Cı/o	I/O Capacitance	Vout = 3dV	7	pF

NOTE:

1. This parameter is guaranteed by device characterization, but not production tested.

Recommended Operating Temperature and Supply Voltage

Grade	Temperature	Vss	V DD	
Commercial	0°C to +70°C	0V	See Below	
Industrial	-40°C to +85°C	0V	See Below	

3834 thi 04

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
V _{DD} ⁽¹⁾	Supply Voltage	3.15	3.3	3.6	٧
V _{DD} ⁽²⁾	Supply Voltage	3.0	3.3	3.6	٧
Vss	Ground	0	0	0	٧
ViH	Input High Voltage	2.0	_	V _{DD} +0.3 ⁽³⁾	٧
VIL	Input Low Voltage	-0.3 ⁽⁴⁾		0.8	٧

3834 tbl 05

NOTES:

- 1. For 71V016SA10 only.
- 2. For all speed grades except 71V016SA10.
- 3. VIH(max.) = VDD+2V for pulse width less than 5ns, once per cycle.
- 4. VIL (min.) = -2V for pulse width less than 5ns, once per cycle.

DC Electrical Characteristics

(VDD = Min. to Max., Commercial and Industrial Temperature Ranges)

			IDT71V016SA		
Symbol	Parameter	Test Condition	Min.	Max.	Unit
lu	Input Leakage Current	VDD = Max., VIN = Vss to VDD		5	μA
ILO	Output Leakage Current	VDD = Max., $\overline{\text{CS}}$ = VIH, VOUT = VSS to VDD		5	μA
Vol	Output Low Voltage	IOL = 8mA, VDD = Min.		0.4	V
Voн	Output High Voltage	Iон = –4mA, VDD = Min.	2.4		V

DC Electrical Characteristics(1,2)

(VDD = Min. to Max., VLC = 0.2V, VHC = VDD - 0.2V)

			71V016SA10	71V01	6SA12	71V01	6SA15	71V01	6SA20	
Symbol	pol Parameter		Com'l Only	Com'l	Ind	Com'l	Ind	Com'l	Ind	Unit
	ICC Dynamic Operating Current $\overline{CS} \le VLC$, Outputs Open, VDD = Max., f = fmax ⁽³⁾	Max.	160	150	160	130	130	120	120	mA
ICC		Typ. ⁽⁴⁾	65	60		55	-	50	1	IIIA
ISB			45	40	45	35	35	30	30	mA
ISB1	Full Standby Power Supply Current (static) $\overline{\text{CS}} \geq \text{VHC}$, Outputs Open, VDD = Max., f = 0 ⁽³⁾		10	10	10	10	10	10	10	mA

NOTES:

1. All values are maximum guaranteed values.

- 2. All inputs switch between 0.2V (Low) and VDD 0.2V (High).
- 3. $f_{MAX} = 1/t_{RC}$ (all address inputs are cycling at f_{MAX}); f = 0 means no address input lines are changing.
- 4. Typical values are based on characterization data for H step only measured at 3.3V, 25°C and with equal read and write cycles.

3834 tbl 08

3834 tbl 07

AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	1.5ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
AC Test Load	See Figure 1, 2 and 3

3834 tbl 09

AC Test Loads

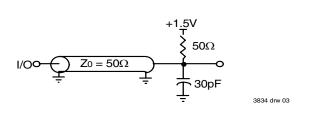
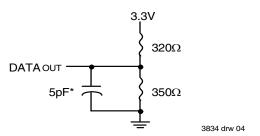


Figure 1. AC Test Load



 $\ensuremath{^{\star}}$ Including jig and scope capacitance.

Figure 2. AC Test Load (for tclz, tolz, tchz, tohz, tow, and twhz)

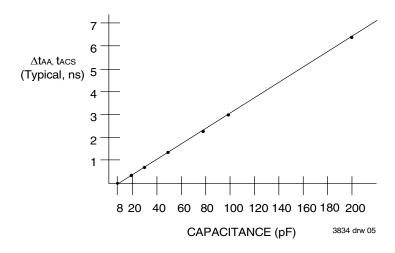


Figure 3. Output Capacitive Derating

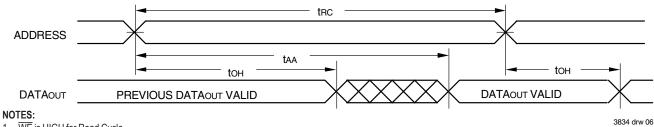
AC Electrical Characteristics (VDD = Min. to Max., Commercial and Industrial Temperature Ranges)

		71V016SA10 ⁽²⁾		71V01	71V016SA12		16SA15	71V01	71V016SA20	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
READ CYCL	E	•			•					
trc	Read Cycle Time	10		12		15		20		ns
taa	Address Access Time	_	10		12		15	_	20	ns
tacs	Chip Select Access Time	_	10		12		15	_	20	ns
ta_z(1)	Chip Select Low to Output in Low-Z	4	_	4	_	5		5	_	ns
tcHz ⁽¹⁾	Chip Select High to Output in High-Z	_	5		6	_	6		8	ns
toE	Output Enable Low to Output Valid	_	5	_	6		7	_	8	ns
toLz ⁽¹⁾	Output Enable Low to Output in Low-Z	0		0	_	0		0	_	ns
tonz ⁽¹⁾	Output Enable High to Output in High-Z	_	5		6	_	6	_	8	ns
tон	Output Hold from Address Change	4	_	4	_	4	_	4	_	ns
tBE	Byte Enable Low to Output Valid	_	5	_	6	_	7		8	ns
tBLZ ⁽¹⁾	Byte Enable Low to Output in Low-Z	0		0	_	0		0		ns
t _{BH} z ⁽¹⁾	Byte Enable High to Output in High-Z	_	5		6	_	6	_	8	ns
WRITE CYC	LE									
twc	Write Cycle Time	10	_	12		15		20		ns
taw	Address Valid to End of Write	7		8		10		12		ns
tcw	Chip Select Low to End of Write	7		8		10		12		ns
tsw	Byte Enable Low to End of Write	7		8		10		12		ns
tas	Address Set-up Time	0		0		0		0		ns
twr	Address Hold from End of Write	0		0	_	0		0		ns
twp	Write Pulse Width	7		8	_	10		12		ns
tow	Data Valid to End of Write	5		6		7		9	_	ns
tон	Data Hold Time	0		0		0		0		ns
tow ⁽¹⁾	Write Enable High to Output in Low-Z	3		3		3		3		ns
twnz ⁽¹⁾	Write Enable Low to Output in High-Z		5		6	_	6		8	ns

3834 tbl 10

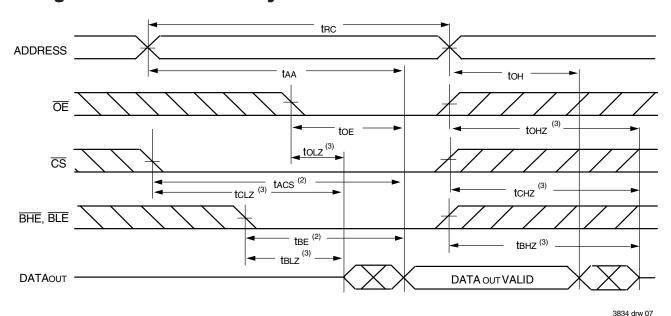
- 1. This parameter is guaranteed with the AC Load (Figure 2) by device characterization, but is not production tested.
- 2. 0°C to +70°C temperature range only.

Timing Waveform of Read Cycle No. 1(1,2,3)



- WE is HIGH for Read Cycle.
- $\underline{\text{Device is }} \text{ continuously selected, } \overline{\text{CS}} \text{ is LOW}.$
- OE, BHE, and BLE are LOW.

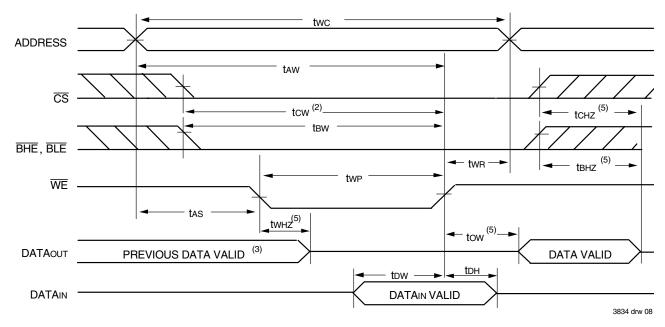
Timing Waveform of Read Cycle No. 2⁽¹⁾



NOTES:

- 1. WE is HIGH for Read Cycle.
- 2. Address must be valid prior to or coincident with the later of \overline{CS} , \overline{BHE} , or \overline{BLE} transition LOW; otherwise tAA is the limiting parameter.
- 3. Transition is measured ±200mV from steady state.

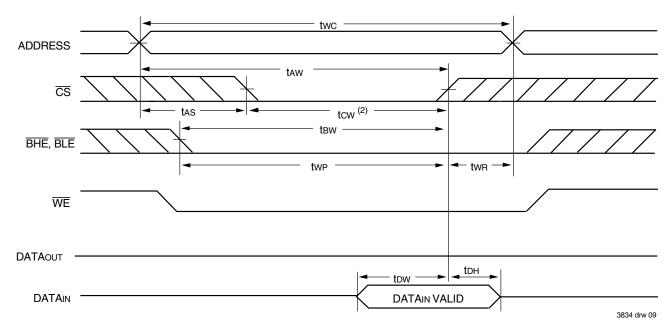
Timing Waveform of Write Cycle No. 1 (WE Controlled Timing)(1,2,4)



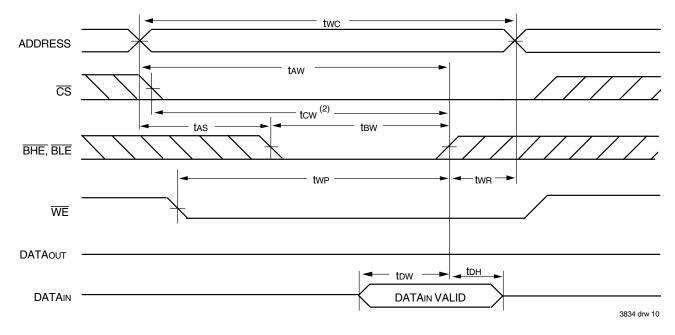
NOTES:

- 1. A write occurs during the overlap of a LOW $\overline{\text{CS}}$, LOW $\overline{\text{BHE}}$ or $\overline{\text{BLE}}$, and a LOW $\overline{\text{WE}}$.
- 2. \overline{OE} is continuously HIGH. If during a \overline{WE} controlled write cycle \overline{OE} is LOW, twp must be greater than or equal to twHz + tow to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If \overline{OE} is HIGH during a \overline{WE} controlled write cycle, this requirement does not apply and the minimum write pulse is as short as the specified twp.
- 3. During this period, I/O pins are in the output state, and input signals must not be applied.
- 4. If the CSLOW or BHE and BLE LOW transition occurs simultaneously with or after the WE LOW transition, the outputs remain in a high-impedance state.
- 5. Transition is measured ±200mV from steady state.

Timing Waveform of Write Cycle No. 2 (CS Controlled Timing)(1,4)



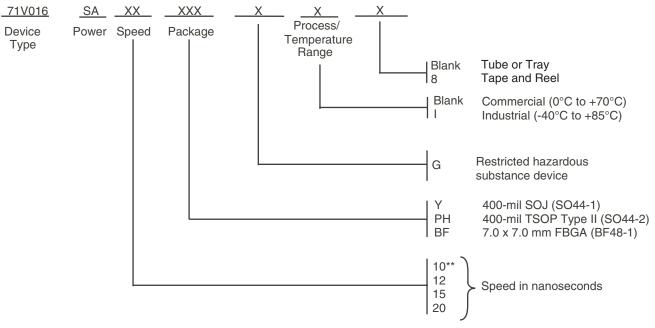
Timing Waveform of Write Cycle No. 3 (BHE, BLE Controlled Timing)(1,4)



NOTES:

- 1. A write occurs during the overlap of a LOW $\overline{\text{CS}}$, LOW $\overline{\text{BHE}}$ or $\overline{\text{BLE}}$, and a LOW $\overline{\text{WE}}$.
- 2. \overline{OE} is continuously \overline{HIGH} . If during a \overline{WE} controlled write cycle \overline{OE} is LOW, twp must be greater than or equal to twHz+ tow to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If \overline{OE} is HIGH during a \overline{WE} controlled write cycle, this requirement does not apply and the minimum write pulse is as short as the specified twp.
- 3. During this period, I/O pins are in the output state, and input signals must not be applied.
- 4. If the $\overline{\text{CS}}$ LOW or $\overline{\text{BHE}}$ and $\overline{\text{BLE}}$ LOW transition occurs simultaneously with or after the $\overline{\text{WE}}$ LOW transition, the outputs remain in a high-impedance state.
- 5. Transition is measured ±200mV from steady state.

Ordering Information



** Commercial temperature range only.

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Datasheet Document History

1/7/00		Updated to new format
	Pp. 1, 3, 5, 8	Added Industrial Temperature range offerings
	Pg. 2	Numbered I/Os and address pins on FBGA Top View
	Pg. 6	Revised footnotes on Write Cycle No. 1 diagram
	Pg. 7	Revised footnotes on Write Cycle No. 2 and No. 3 diagrams
	Pg. 9	Added Datasheet Document History
08/30/00	Pg. 3	Tighten Icc and IsB.
	Pg. 5	Tighten tclz, tchz, tohz, tbhz and twhz
08/22/01	Pg. 8	Removed footnote "available in 15ns and 20ns only"
06/20/02	Pg. 8	Added tape and reel field to ordering information
01/30/04	Pg. 8	Added "Restricted hazardous substance device" to ordering information.
09/27/06	Pg. 8	Corrected ordering information, changed position of I and G.
02/14/07	Pg.8	Added H step generation to data sheet ordering information.
06/26/07	Pg.3	Changed typical parameters for ICC, DC electrical characteristics table.
10/13/08	Pg.8	Removed "IDT" from orderable part number
10/11/11	Pg.1,8	Updated datasheet with removal of Obsolete HSA part number.



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